

FIG.1

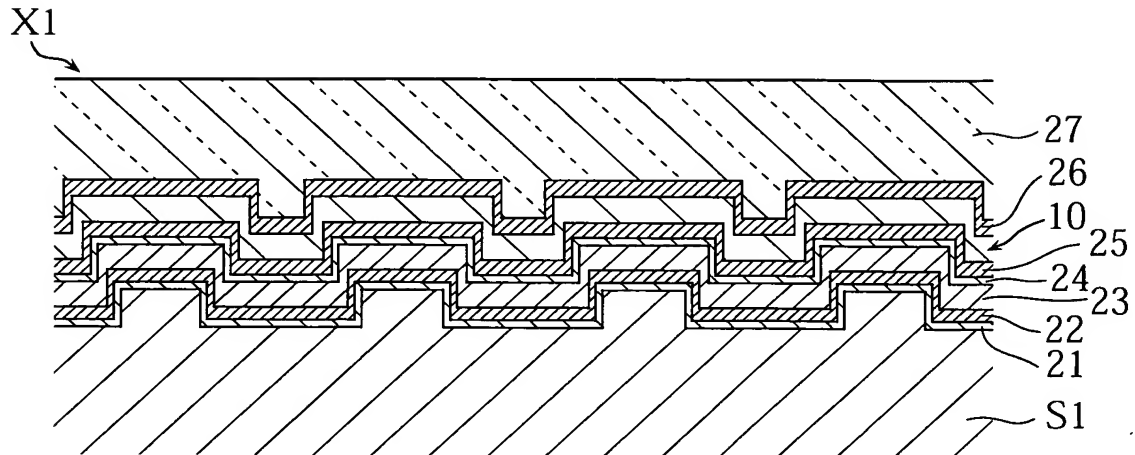


FIG.2

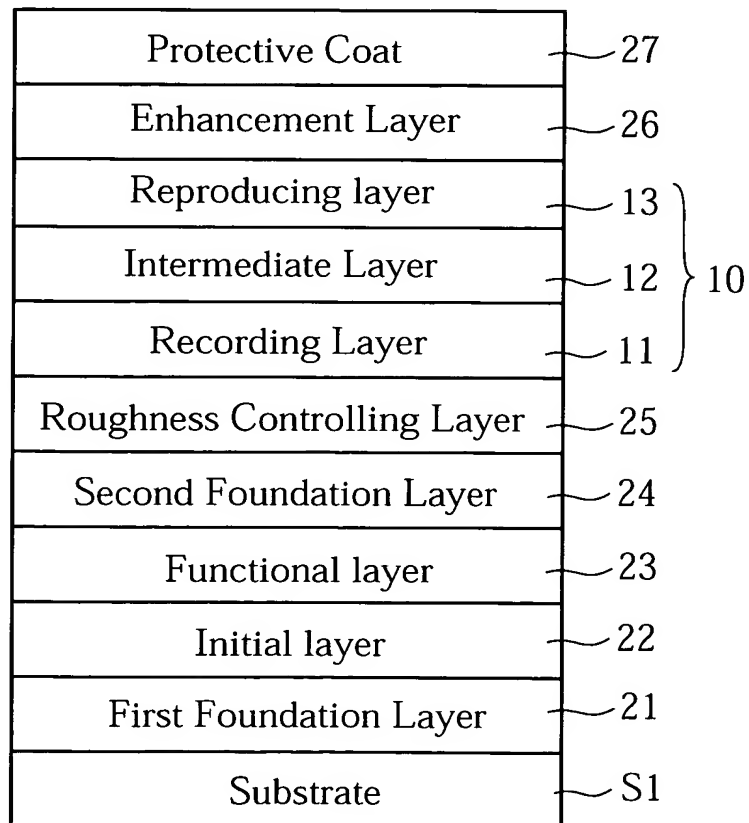


FIG.3A

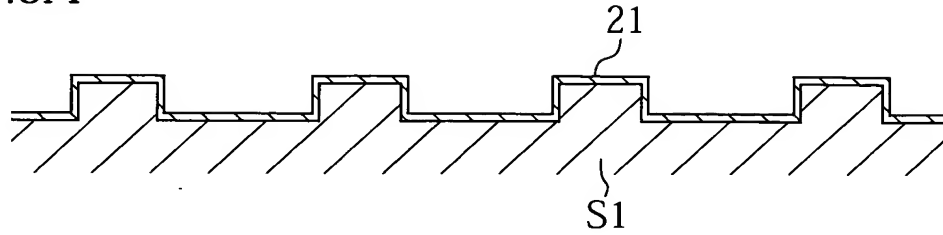


FIG.3B

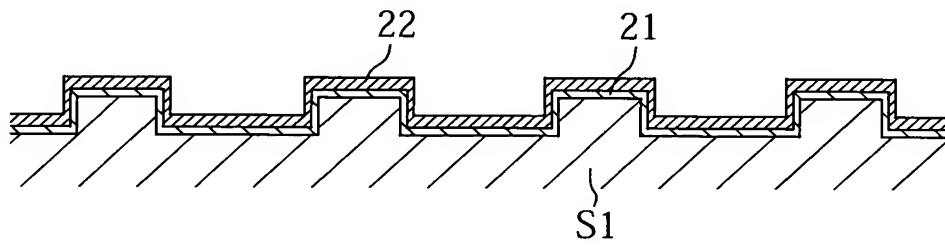


FIG.3C

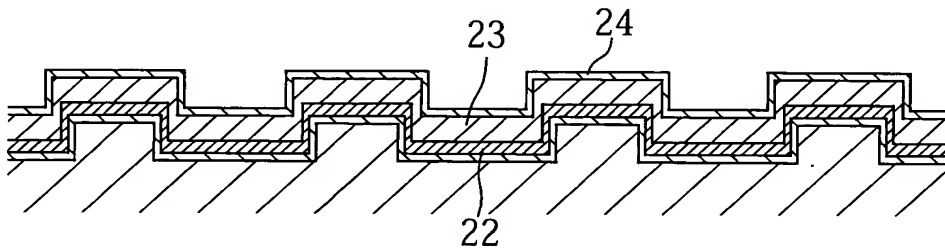


FIG.3D

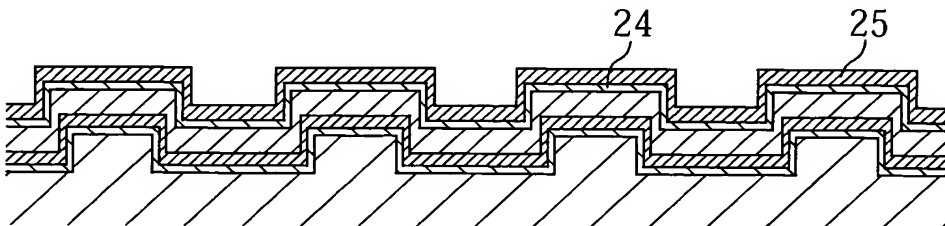


FIG.4A

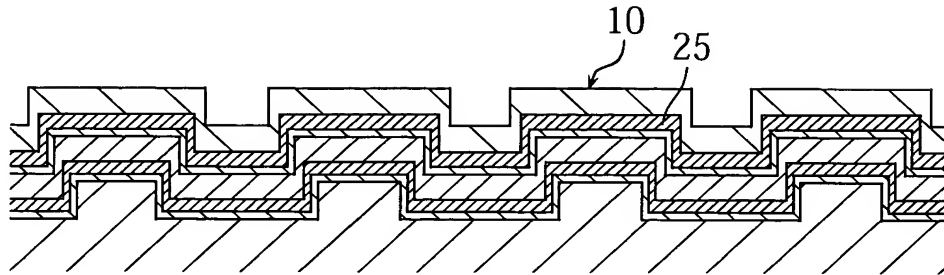


FIG.4B

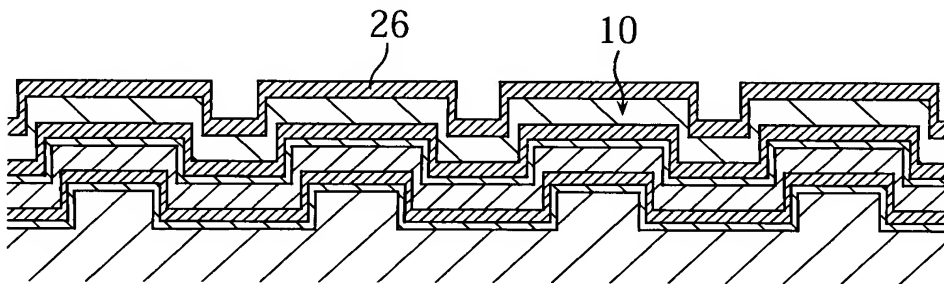


FIG.4C

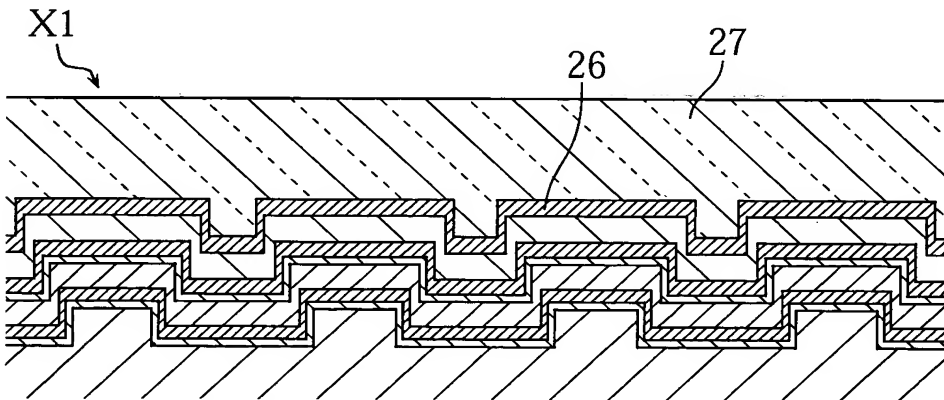


FIG.5A

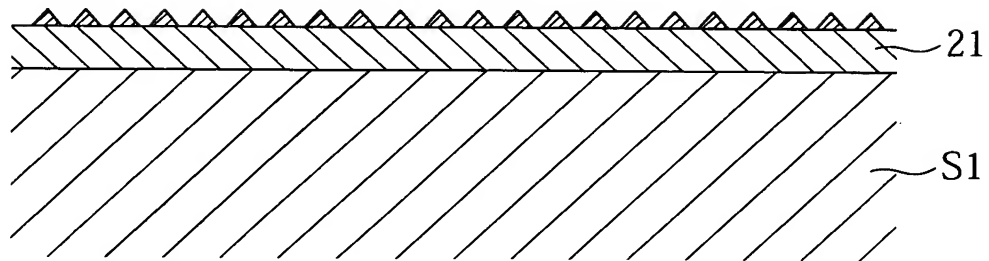


FIG.5B

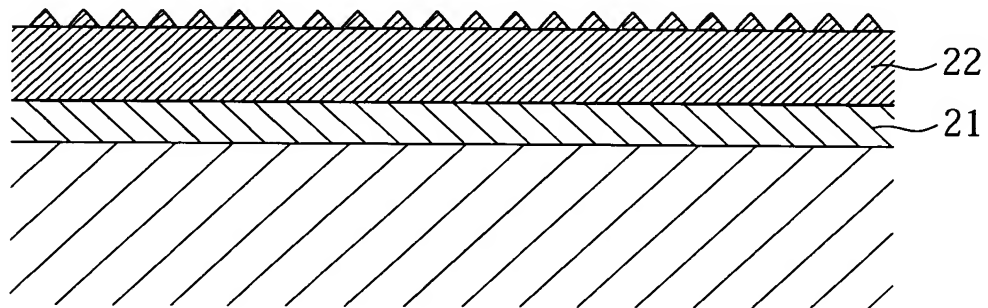


FIG.6A

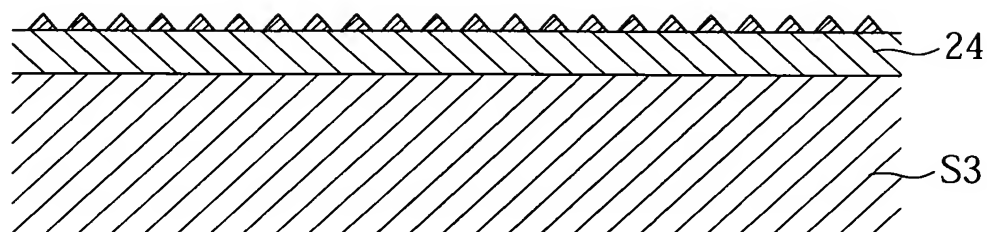


FIG.6B

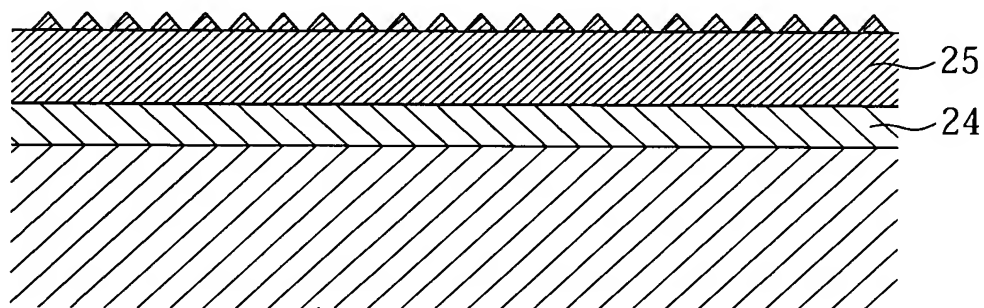


FIG.7

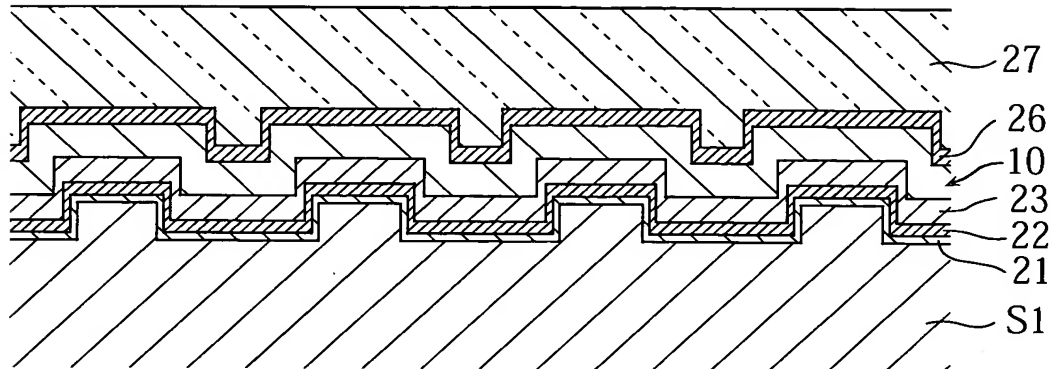


FIG.8

	APS (nm)	R a (nm)	P - V (nm)
Sample A	7.6	0.69	5.9
Sample B	15.2	0.72	6.3
Sample C	23.5	0.73	8.5
Sample D	34.7	0.98	9.5

FIG.9

Roughness Controlling Layer (Pt, 1nm)
Second Foundation Layer (SiN, 5nm)
Heat Sink Layer (AlSi, 30nm)
Initial Layer (Pt, 1nm)
First Foundation Layer (SiN, 2nm)
Substrate (Glass)

FIG.10

Heat Sink Layer (AlSi, 30nm)
Initial Layer (Pt, 1nm)
First Foundation Layer (SiN, 2nm)
Substrate (Glass)

FIG.11

Roughness Controlling Layer (Pt, 1nm)
Heat Sink Layer (AlSi, 30nm)
Substrate (Glass)

FIG.12

Heat Sink Layer (AlSi, 30nm)
Substrate (Glass)

FIG.13

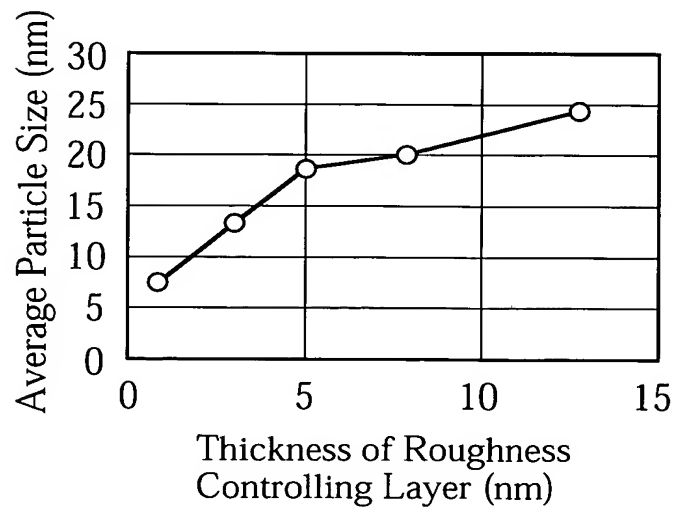


FIG.14

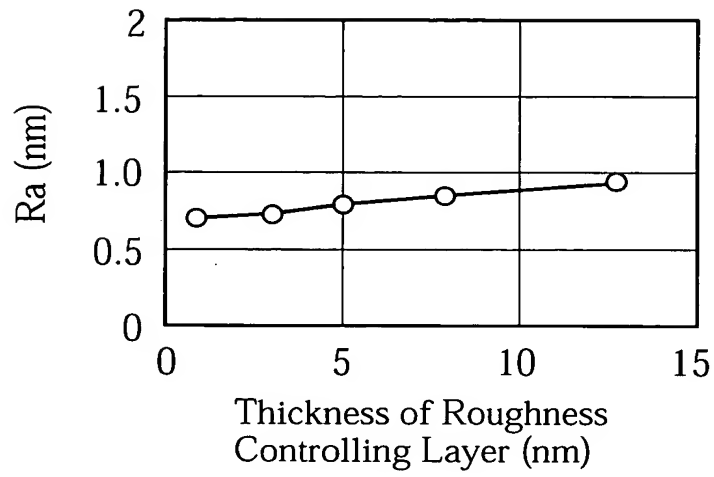


FIG.15

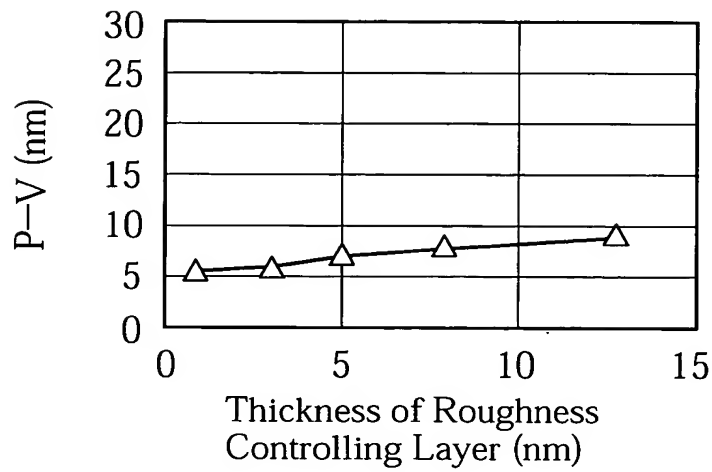


FIG.16

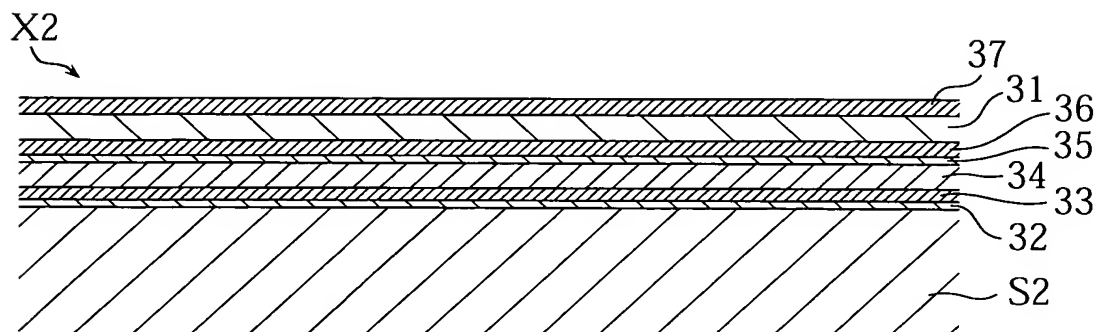


FIG.17

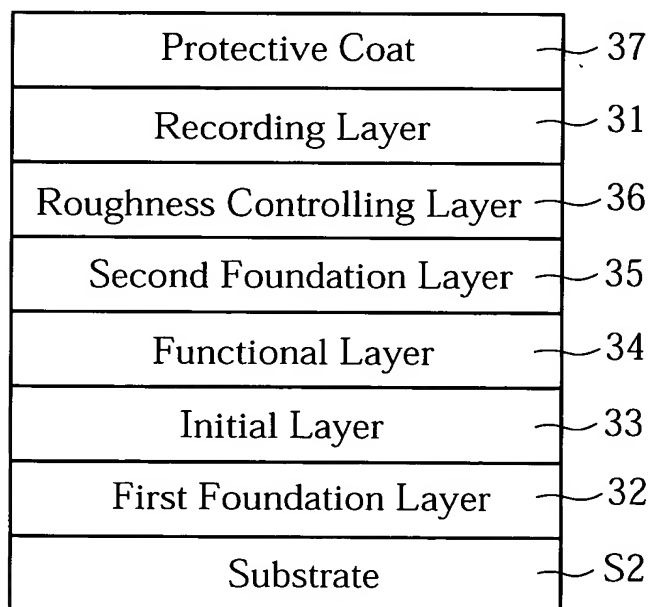


FIG.18

Protective Coat (Transparent Resin, 15 μ m)
Enhancement Layer (SiN, 35nm)
Recording Layer (Tb ₂₂ Fe ₆₂ Co ₁₆ , 50nm)
Roughness Controlling Layer (Pt, 1nm)
Second Foundation Layer (SiN, 5nm)
Heat Sink Layer (AlSi, 30nm)
Initial Layer (Pt, 1nm)
First Foundation Layer (SiN, 2nm)
Substrate (Glass)

FIG.19

Protective Coat (Transparent Resin, 15 μ m)
Enhancement Layer (SiN, 35nm)
Recording Layer (Tb ₂₂ Fe ₆₂ Co ₁₆ , 50nm)
Roughness Controlling Layer (Pt, 1nm)
Heat Sink Layer (AlSi, 30nm)
Substrate (Glass)

FIG.20

Protective Coat (Transparent Resin, 15 μ m)
Enhancement Layer (SiN, 35nm)
Reproducing Layer (Gd ₂₇ Fe ₆₅ Co ₈ , 20nm)
Intermediate Layer (Tb ₂₂ Fe ₇₈ , 15nm)
Recording Layer (Tb ₂₂ Fe ₆₂ Co ₁₆ , 70nm)
Roughness Controlling Layer (Pt, 1nm)
Second Foundation Layer (SiN, 5nm)
Heat Sink Layer (AlSi, 30nm)
Initial Layer (Pt, 1nm)
First Foundation Layer (SiN, 2nm)
Substrate (Glass)

FIG.21

Protective Coat (Transparent Resin, 15 μ m)
Enhancement Layer (SiN, 35nm)
Reproducing Layer (Gd ₂₇ Fe ₆₅ Co ₈ , 20nm)
Intermediate Layer (Tb ₂₂ Fe ₇₈ , 15nm)
Recording Layer (Tb ₂₂ Fe ₆₂ Co ₁₆ , 70nm)
Roughness Controlling Layer (Pt, 1nm)
Heat Sink Layer (AlSi, 30nm)
Substrate (Glass)

FIG.22

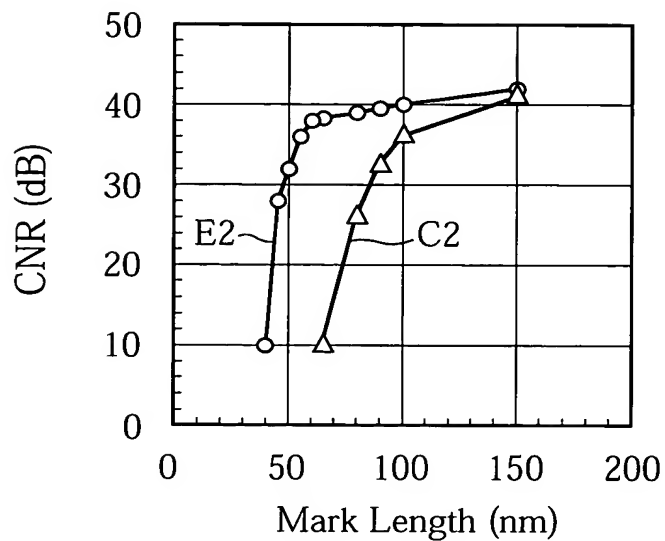


FIG.23

